	Type	Hits	Search Text	DBs	Time Stamp	Common	Error	
Н	BRS	719	(adhesive near resin) with (chip or die)	USPAT; US-PGPUB; EPO;	2001/11/12 10.55		Definition	
2	BRS	5.1	with (chip or	JPO; DERWENT; IBM TDB USPAT; US-PGPUB: RPO:		***************************************		
1 0	0 0	110	h (chin or die))		2001/11/13 10:56			***************************************
n	BKS	7.15			2001/11/13 10:56			
4	BRS	83	<pre>((danesive near resin) with (chip or die)) and tape) and (water or vapor or moisture or porous or gap or stress)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:26			
20	BRS	-1	"5703405". PN.	USPAT		,		
, [-	BRS			IUSPAT ITSDATI	2001/11/13 11:13			
ω	BRS	23349	((water or vapor or moisture or porous or gap or stress) with tape)	USPAT; US-PGPUB; EPO; IPO: DERWENT: IMM IND	2001/11/13 15:53		A-41 TH COLUMN TO SERVED THE PARTY OF THE PA	
o l	BRS	21140	((water or vapor or moisture or porous or gap)with tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:42			
10	BRS	119	(((water or vapor or moisture or porous or gap or stress) with tape)) and (adhesive adj resin)	USPAT; US-PGPU JPO; DERWENT;	2001/11/13 11:30			
11	BRS	113	or moisture or porous or tape)) and (adhesive adj ssive near resin) with (chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:31			
12	BRS	35	((((water or vapor or moisture or porous or gap or stress)with tape)) and (adhesive adjresin)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:43		***************************************	
13	BRS	1818	((water or vapor or moisture or porous or gap or stress)near tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:43			
44	BRS	35	((((Water or vapor or moisture or porous or gap or stress) with tape)) and (adhesive adjresin)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:53			
15	BRS	0	·	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:44			The state of the s
16	BRS	2622	PACE OR HOLE) NEAR	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/11/13 11:46		Truncation Overflow. Return string	
17	BRS	420	((POR\$ OR GAP OR STRESS OR SPACE OR HOLE) NEAR TAPE) and (chip or die)	SPACE OR HOLE) NEAR USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 15:49		5 U.U.POR	
18	BRS	1 1	SPACE OR HOLE)) AND ADHESIVE AND	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:52		***************************************	
19	BRS	3579	((ball or bump) with tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:51		***************************************	
20	BRS	381	or bump) near tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:52		***************************************	··········
21	BRS	81	near tape)) AND ADHESIVE AND		2001/11/13 11:52			
	Ì	3	mp) near tape)) AND ADHESIVE AND ip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 12:29		***************************************	
23	IS&R				2001/11/13 12:29			mų į

	Type	# .i	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Erro
FI	BRS	e H	13	(POR\$ NEAR TAPE) and (chip or die)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM	2001/11/13 15:51		Truncation Overflow. Return string from Server is: 5.0.0 Por	rs T
2	BRS	1. 4.	10891	USPAT; USPAT; US-PGPU ((water or vapor or moisture)with B; EPO; tape) DERWENT ; IBM TDB	USPAT; US-PGFU B; EPO; JPO; DERWENT ; IBM	2001/11/13 15:54			0
м	BRS	L5	1217	L4 and (chip or die)	T; GPU PO; ENT	2001/11/13			0
	BRS	Гe	597	L5 and (hole\$ or porous or pore 5 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	D'S E	2001/11/13 16:09		Truncation Overflow. Return string from Server is: 5'0'0'HOL	-
	BRS	177	248	U L5 and ((hole\$ or porous or pore U or gap) with (tape or polyimide)) U i	D 14 H	2001/11/13 16:30		Truncation Overflow. Return string from Server is: 5'0'0'HOL	r-4
	BRS	1.8	538	0 257/668.ccls. and (tape or J B polyimide) 1. (1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM	2001/11/13 16:31			0
	BRS	F3	132	U U U U U U U U U U U U U U U U U U U	USPAT; US-PGPU B; EPO; JPO; JERWENT ; IBM	2001/11/13 16:32		0	
— "	BRS	L10	146	L8 and (water or moisture or TB yapor or crack) TO D D D D D D D D D D D D D D D D D D D	USPAT; US-PGPU B; EPO; 20 JPO; DERWENT TIBM TDB	2001/11/13 16:44		0	





Type	T #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Erro
BRS	111	44	257/736.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGFU B; EPO; JPO; DERWENT ; IBM	2001/11/13 16:45			8
BRS	112	300	257/737.ccls. and (water or moisture or vapor or crack)	NT; GPU IPO; ENT	201/11/13 16:45			0
BRS	L133	235	257/738.ccls. and (water or moisture or vapor or crack)	T; GPU PO; ENT	2001/11/13 16:45			0
BRS	L14	123	257/719.ccls. and (water or moisture or vapor or crack)	D: H	2001/11/13 16:45			0
BRS	L15	312	257/778.ccls. and (water or moisture or vapor or crack)	D	2001/11/13 16:46			0
BRS	L16	201	257/783.ccis. and (water or moisture or vapor or crack)	D % F	2001/11/13 16:46		0	_
BRS	L17	171	257/678.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM	2001/11/13 16:46		0	
BRS	L18	184 1	257/668.ccls. and (water or moisture or vapor or crack)	AT; PGPU SPO; NENT	2001/11/13 16:46		0	



	\dashv	Type	# -	Hits	Search Text	DBs Time Stamm	-		1
		BRS	L3	H 33	(POR\$ NEAR TAPE) and (chip or die)	USPAT; US-PGPU B; EPO; JPO; DERWENT 15:51 ; IBM	Commenter	Error Definition Truncation Overflow. Return string from Server is:	rs 1
- 2		BRS		10891	((water or vapor or moisture) with B: EPO; tape) tape) i IBM (TRM TRM TRM TRM TRM TRM TRM TRM TRM TRM	USPAT; US-PCPU US-PCPU US-PCP; UPO; UPO; UFS-FF UFS			0
m	BF	BRS	1.5	1217	L4 and (chip or die)	USPAT; US-PGPU B; EPO; UPO; UPO; 16:07 ; IBM TOB			0
4,	BRS		16	597	L5 and (hole\$ or porous or pore or gap)	USPAT; US-PGPU B: EPO; JPO; JENEWENT 16:09 L: IBM TDB	F II () ()	Truncation Overflow. Return string from Server is: 5'0'0'HOL	-
20	BRS		L7	248	L5 and ((hole\$ or porous or pore or gap) with (tape or polyimide))	USPAT; US-PGFU B; EFO; UPO; UPO; DERWENT 16:30 TDB	FKKNN	Truncation Overflow. Return string from Server is: 5.0.0 HOL	
vo	BRS		L8	538	257/668.ccls. and (tape or polyimide)	USPAT, US-PGPU B; EPO; 2001/11/13 JFO; 16:31 ; IBM TDB			0
	BRS	1.9		132	L8 and (water or moisture or J vapor)	USPAT; US-PGPU B; EPO; 2001/11/13 JPO; DERWENT 16:32 ; IBM		0	
	BRS		L10	146 T	U Us and (water or moisture or B U U Vapor or crack)	USPAT; US-PGPU B; EPO; 2001/11/13 JPO; DERWENT 16:44 ; IBM		0	

	Type	#	Hits	Search Text	DBs Time	Stamp Comments	Error Definition	Erro
6	BRS	1 1 1	44	257/736.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPU B; EPO; JPO; JERWENT 16:45 ; IBM	13		0
10	BRS	112	300	257/737.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPU B; EPO; 2001/11/13 JPO; 16:45 T IBM TDB	13		0
	BRS	L13	235	257/738.ccls. and (water or moisture or vapor or crack)	USPAI; US-PGPU B; EPO; JPO; JPO; 16:45 ; IBM TDB	13		0
12	BRS	L14	123	257/719.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPU B; EPO; 2001/11/13 JFO; 16:45 ; IBM TDB	13		0
E -	BRS	L15	312	257/778.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPU B; EPO; 2001/11/13 JPO; 16:46 ; IBM	13		0
14	BRS	L16	201	257/783.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGFU B: EPO; JPO; DERWENT 16:46 ; IBM	13		0
15	BRS	117	171	257/678.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPU B; EPO; 2001/11/13 JPO; DERWENT 7 IBM	13		0
9 1	BRS	L18	184		USPAT; US-PGPU B; EPO; 2001/11/13 JPO; 16:46 JERWENT TDB	13		0
	BRS		1825	ermeab\$ or	USPAT 2001/11/13	13		0
18	BRS	L20	431	(semiconductor or chip or	USPAT 2001/11/13	13		0



	Type	# 17	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Err
19	9 BRS	121	18	L19 and (g/m)	USPAT	2001/11/13 16:54			
20) BRS	122	25	(tape or resin) and ((water or moisture or vapor) with (g/m))	USPAT	2001/11/13 17:10			0
21	1 BRS	L23	28	(g/m)) and vapor)	USPAT	2001/11/13 17:12			
22	2 BRS	L24	2		USPAT	2001/11/13 17:09			0
23	BRS	1.25	വ	<pre>tape and ((water or moisture or vapor) with (g/m))</pre>	USPAT	2001/11/13 17:10			0
24	BRS	L26	7	L23 and ((semiconductor adj device) or chip or die)	USPAT	2001/11/13 17:12		444	0